

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6801xxxxPR-G

Typical Mass: 57 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.727	Silicon	12800	7440-21-3
		- Arsenic	<1	7440-38-2
Leadframe	24.392	Copper	427900	7440-50-8
		Tin	300	7440-31-5
		Silver	3800	7440-22-4
Die attach	0.126	Silver	2200	7440-22-4
		Epoxy	600	—
Bonding wire	0.116	Gold	2000	7440-57-5
Resin	26.757	Silica	469400	60676-86-0
		Epoxy resin	38300	—
		Phenol resin	27600	—
		Metal hydroxide	7500	—
Plating	0.430	Tin	7500	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."